



# OBJECTIVE ANALYSIS

Semiconductor Market Research

# Coughlin Associates

Data Storage Consulting

## EMERGING MEMORIES TAKE OFF

*Now Available*

### **Abstract:**

Emerging memories have begun their campaign to replace established memory technologies in SoCs. Meanwhile, stand-alone emerging memory chips, like MRAM, FRAM, and ReRAM, are winning designs in new applications. Intel's 3D XPoint memory-based Optane products are shipping in high volume in both DIMM and data center SSD formats. The market is poised to grow significantly over the next decade.

Who will profit from this change? Semiconductor makers who understand the emerging memory market will not be the only ones to thrive. Users of these new chips can gain a competitive edge by becoming early adopters, tool makers will see growth from the tooling changes, and investors can tap into an important growth market. For all of these businesses this report provides the basis for an effective emerging memory strategy.

This 218-page study is an extensive update to the widely-acclaimed 2020 report by Objective Analysis and Coughlin Associates. Through its 155 figures and 36 tables readers learn all about the leading emerging memory technologies and their interaction with standard memories, both as stand-alone memory chips and in embedded applications (the memories within logic SoCs like ASICs and MCUs).

The study provides a deep and resourceful mix of technical information, market dynamics, forecasts, and competitive analyses of leading companies. Detailed forecasts predict how the market for emerging memories will grow as well as the markets for the capital equipment used to produce them. Vendor profiles detail the strategies and technologies of both established market participants and start-ups.

We present the market drivers for these new technologies and show how the technology fits into the competitive memory chip landscape, explaining how successful companies can profit from fast-growing emerging memory markets. This report provides essential information for creating your company's successful emerging memory strategy.

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